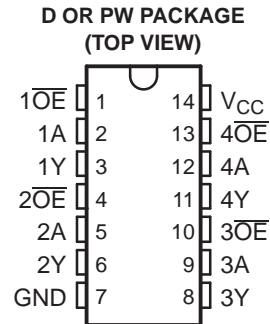


3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

FEATURES

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <math><0.8\text{ V}</math> at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- I_{off} Supports Partial-Power-Down Mode Operation
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors



DESCRIPTION/ORDERING INFORMATION

This bus buffer is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVT125-Q1 features independent line drivers with 3-state outputs. Each output is in the high-impedance state when the associated output-enable (\overline{OE}) input is high.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Tape and reel	SN74LVT125QDRQ1	LVT125Q
	TSSOP – PW	Tape and reel	SN74LVT125QPWRQ1	LVT125Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

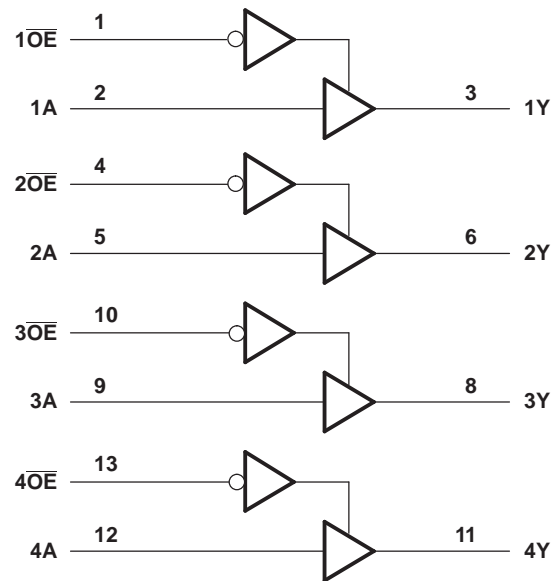


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FUNCTION TABLE

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	H
L	L	L
H	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high state or power-off state ⁽²⁾	-0.5	7	V
I_O	Current into any output in the low state		128	mA
I_O	Current into any output in the high state ⁽³⁾		64	mA
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	D package	86	°C/W
		PW package	113	
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This current flows only when the output is in the high state and $V_O > V_{CC}$.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage		5.5	V
I_{OH}	High-level output current		-32	mA
I_{OL}	Low-level output current		32	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
	Outputs enabled			
T_A	Operating free-air temperature	-40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IK}	$V_{CC} = 2.7\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V
V_{OH}	$V_{CC} = \text{MIN to MAX,}^{(2)}$	$I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$			V
	$V_{CC} = 2.7\text{ V}$,	$I_{OH} = -8\text{ mA}$	2.4			
	$V_{CC} = 3\text{ V}$	$I_{OH} = -32\text{ mA}$	2			
V_{OL}	$V_{CC} = 2.7\text{ V}$	$I_{OL} = 100\ \mu\text{A}$			0.2	V
		$I_{OL} = 24\text{ mA}$			0.5	
	$V_{CC} = 3\text{ V}$	$I_{OL} = 16\text{ mA}$			0.4	
		$I_{OL} = 32\text{ mA}$			0.5	
I_I	$V_{CC} = 0\text{ or MAX,}$	$V_I = 5.5\text{ V}$			40	μA
		$V_I = V_{CC}\text{ or GND}$	Control inputs		± 1	
	$V_{CC} = 3.6\text{ V}$	$V_I = V_{CC}$	Data inputs		1	
		$V_I = 0$			-5	
I_{off}	$V_{CC} = 0$,	$V_I\text{ or }V_O = 0\text{ to }4.5\text{ V}$			± 450	μA
$I_{I(\text{hold})}$	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$	Data inputs	75		μA
		$V_I = 2\text{ V}$		-75		
I_{OZH}	$V_{CC} = 3.6\text{ V}$,	$V_O = 3\text{ V}$			5	μA
I_{OZL}	$V_{CC} = 3.6\text{ V}$,	$V_O = 0.5\text{ V}$			-5	μA
I_{CC}	$V_{CC} = 3.6\text{ V, }V_I = V_{CC}\text{ or GND, }I_O = 0$	Outputs high		0.12	0.35	mA
		Outputs low		4.5	7	
		Outputs disabled		0.12	0.4	
$\Delta I_{CC}^{(3)}$	$V_{CC} = 3\text{ V to }3.6\text{ V}$,	One input at $V_{CC} - 0.6\text{ V}$,	Other inputs at V_{CC} or GND		0.2	mA
C_I	$V_I = 3\text{ V or }0$			4		pF
C_O	$V_O = 3\text{ V or }0$			8		pF

(1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

(3) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

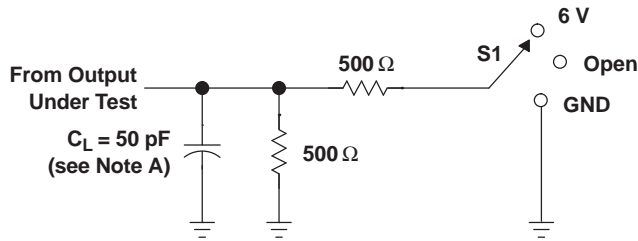
Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3$ V ± 0.3 V			$V_{CC} = 2.7$ V		UNIT
			MIN	TYP ⁽¹⁾	MAX	MIN	MAX	
t_{PLH}	A	Y	1	2.7	4.2	4.7		ns
t_{PHL}			1	2.9	4.1	5.1		
t_{PZH}	\overline{OE}	Y	1	3.4	4.9	6.2		ns
t_{PZL}			1.1	3.4	4.9	6.7		
t_{PHZ}	\overline{OE}	Y	1.8	3.7	5.3	5.9		ns
t_{PLZ}			1.3	2.6	4.7	4.2		

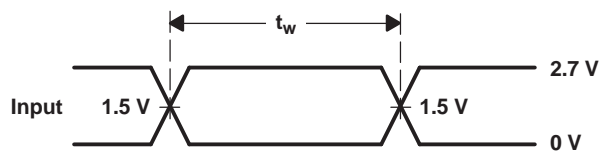
(1) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION

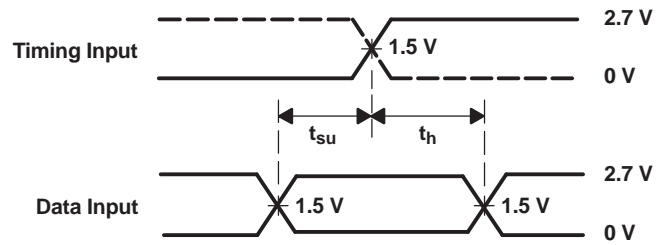


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

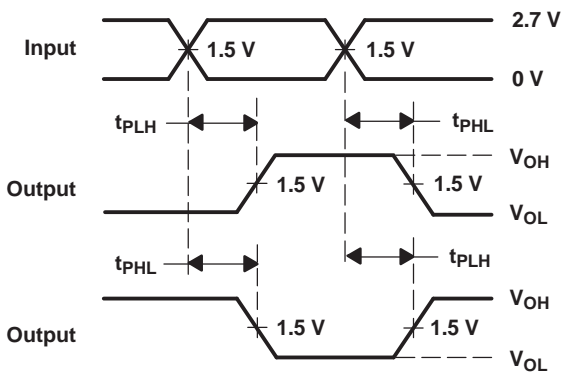
LOAD CIRCUIT FOR OUTPUTS



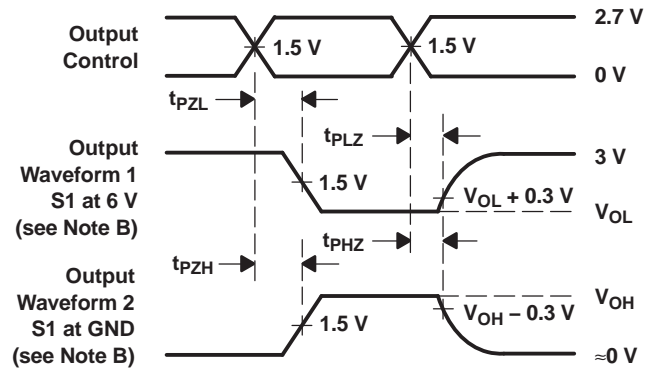
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVT125QDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT125QDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT125QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT125QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVT125-Q1 :

- Catalog: [SN74LVT125](#)
- Enhanced Product: [SN74LVT125-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

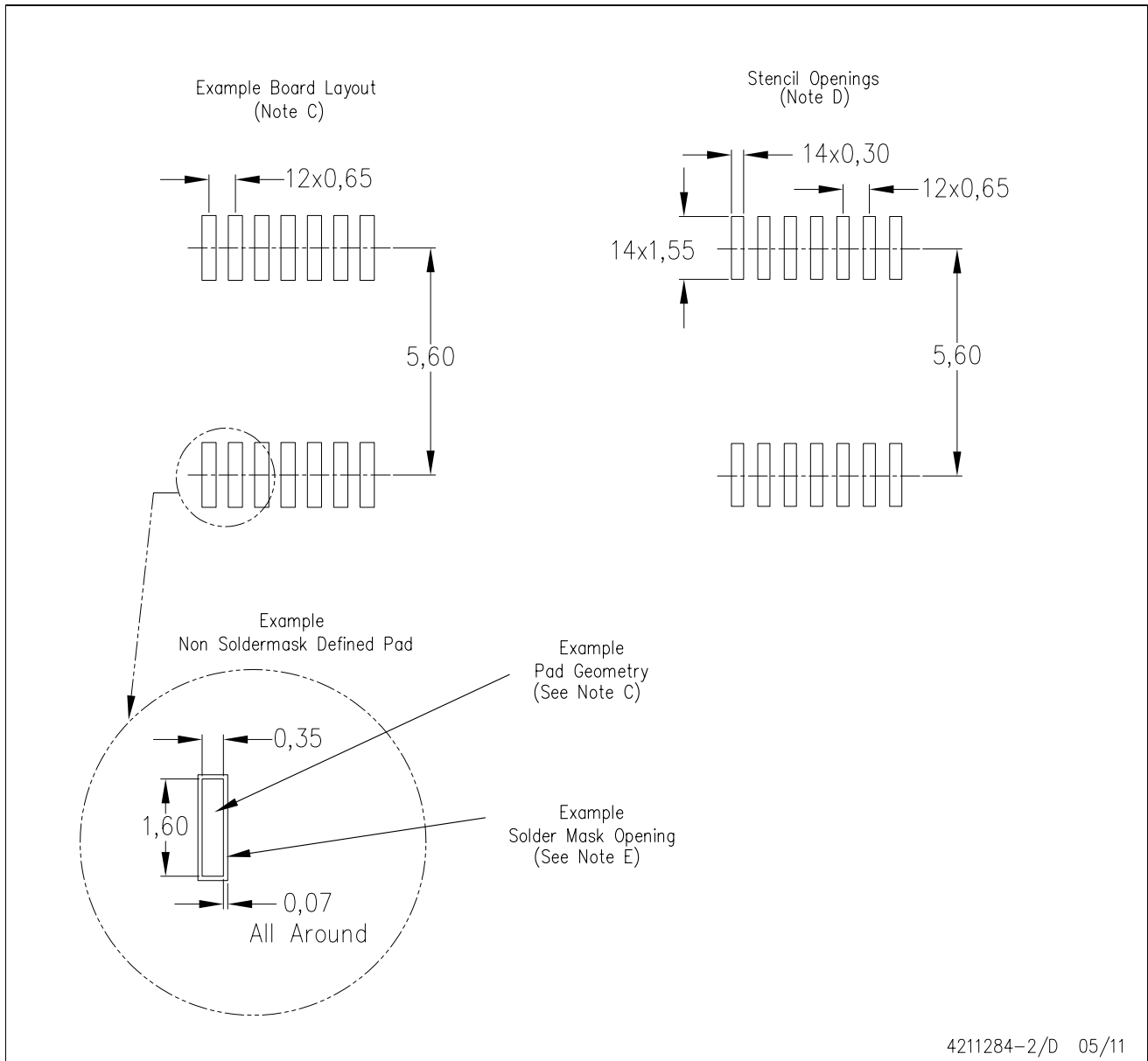


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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